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Laser Beam Scanning (LBS): The Ideal Solution for AR Wearable Applications

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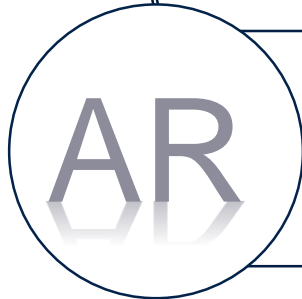
SPIE.ARVRR



Definitions



Virtual Reality – Occluded view and a fully immersive experience



Augmented Reality – Simple digital content is overlaid onto physical world



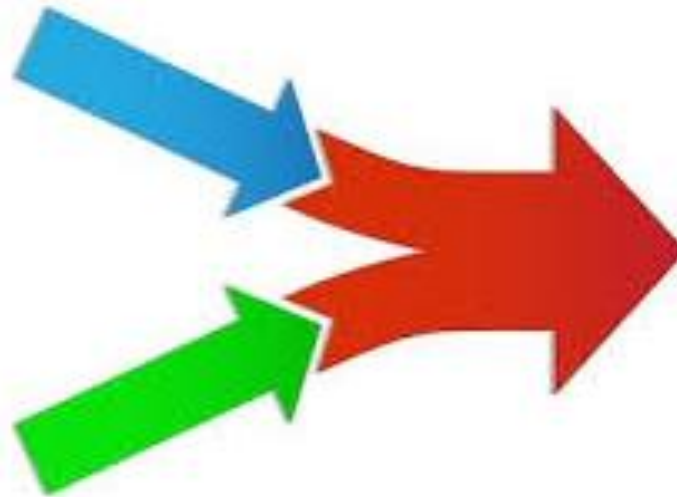
Mixed Reality – Physical and Virtual worlds are fully merged with visually accurate depth, perspective, texture, shade etc.

The Main Challenge

Source: <https://www.forbes.com/sites/solrogers/2019/09/11/what-we-know-about-hololens-2/#2885224d4662>



Source: <https://variety.com/2019/digital/news/magic-leap-mobile-ar-1203109944/>



Source: <https://www.slashgear.com/north-focals-smart-glasses-price-change-prescription-lenses-showroom-tour-14565763/>



- To achieve the desired form factor key determinants, to first order, are:
 - ❖ Near-to-eye compact display technology
 - ❖ Highly efficient combiner optics technology
- Start with simple and broadly useful applications → smart glasses
- Then, add additional functionality as technology & solutions mature

Key requirements for AR wearable devices

Goal: Head-up, Hands-free, All-day-wearable AR glasses which means glasses must be usable, comfortable with the requisite performance

Indoor and outdoor use

Form factor

Low Power (system)

Light weight

Low latency (motion to photon)

Range of FoV

Range of resolution

Eyebox size



Peak brightness > 1000 cd/m² (transparent lenses)



Fashionable eyeglasses



< 1W



< 70g



< 4ms



30° – 40° (AR) to > 80° (MR/XR)



720P (AR) to > 1400P (MR/XR)

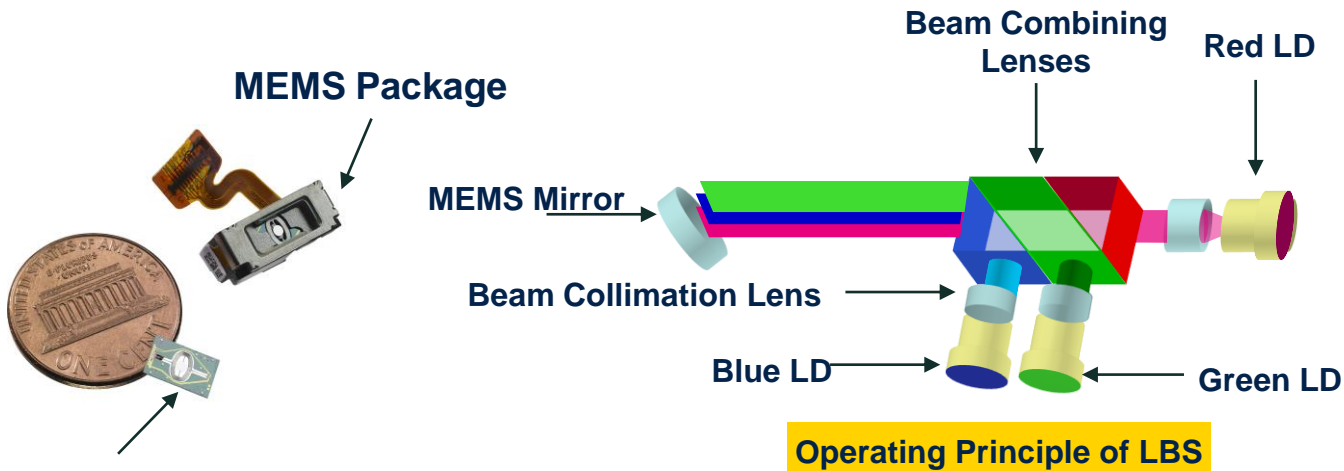


> 10mm x 10mm

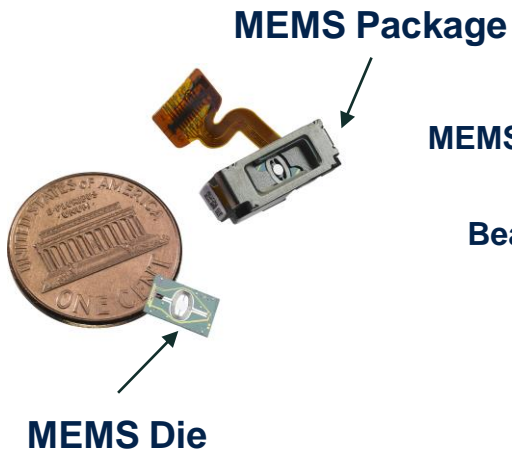
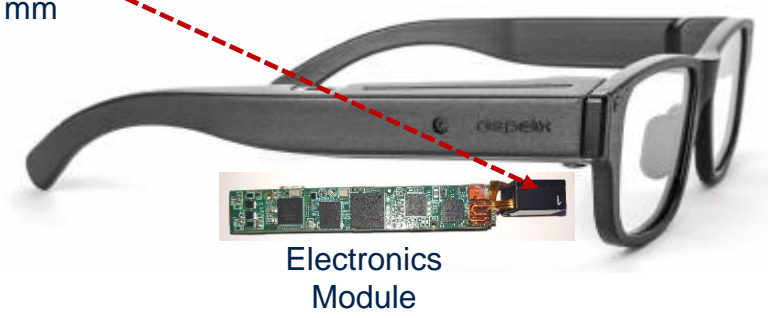
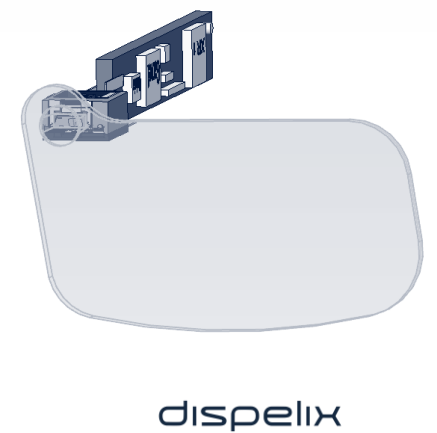
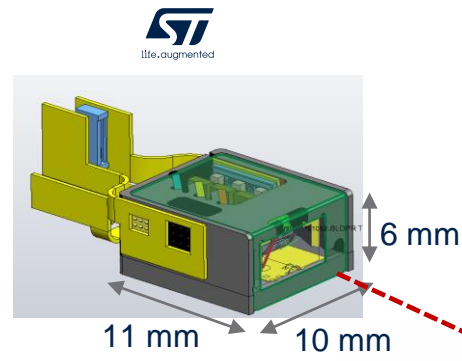
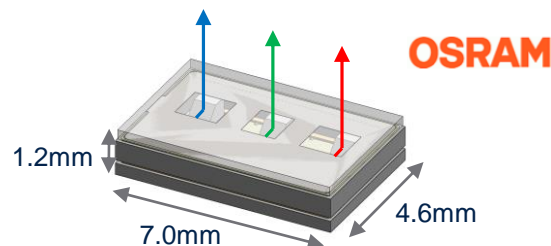
Laser Beam Scanning (LBS) – The Ideal Solution

Ultra small microdisplay
Compact illumination source
High brightness (light engine)
Low Power (system)
Thin, lightweight lenses

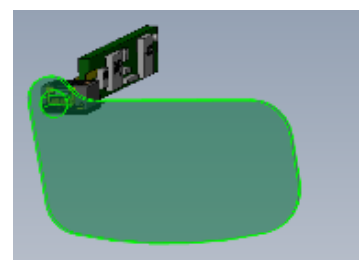
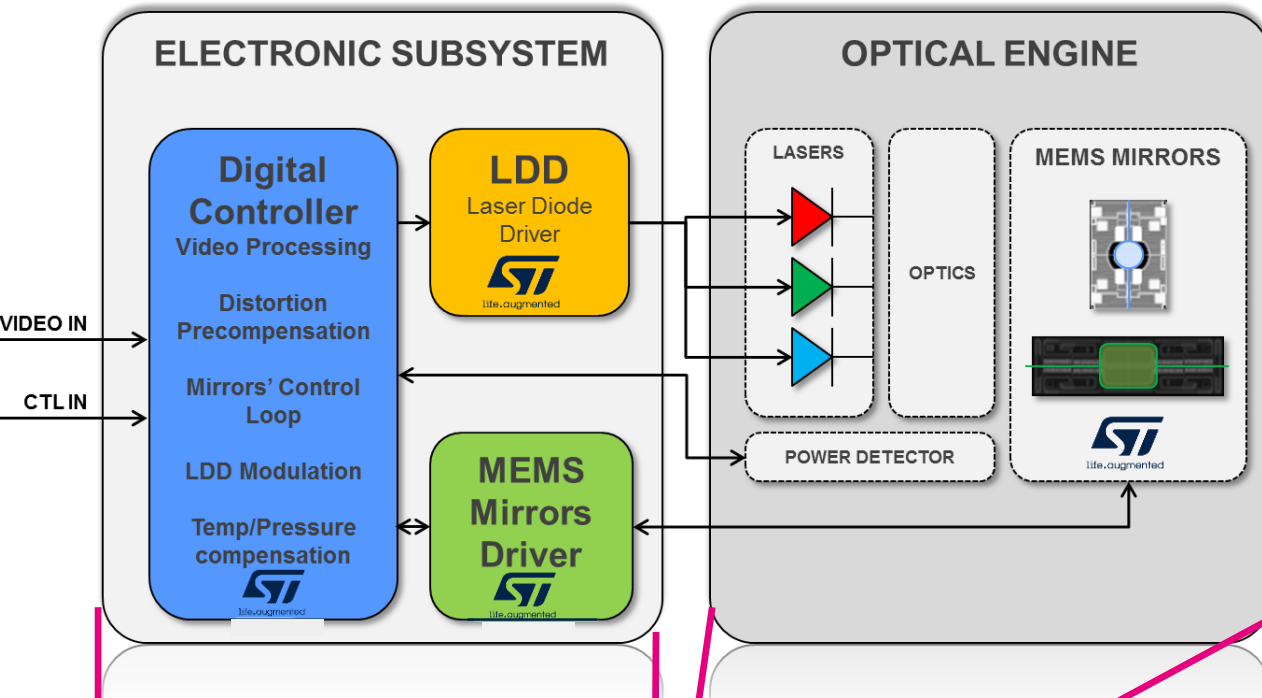
MEMS Micromirror with LBS
Advanced laser diode packaging
>10⁶ cd/m² (nits)
< 1W
DOE or HOE Waveguides



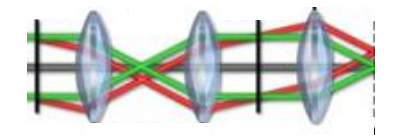
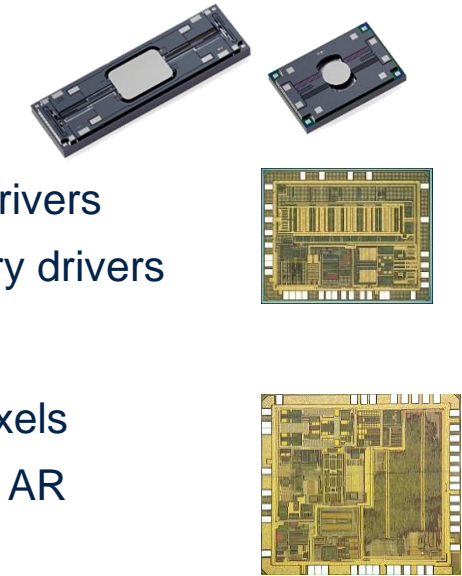
Operating Principle of LBS



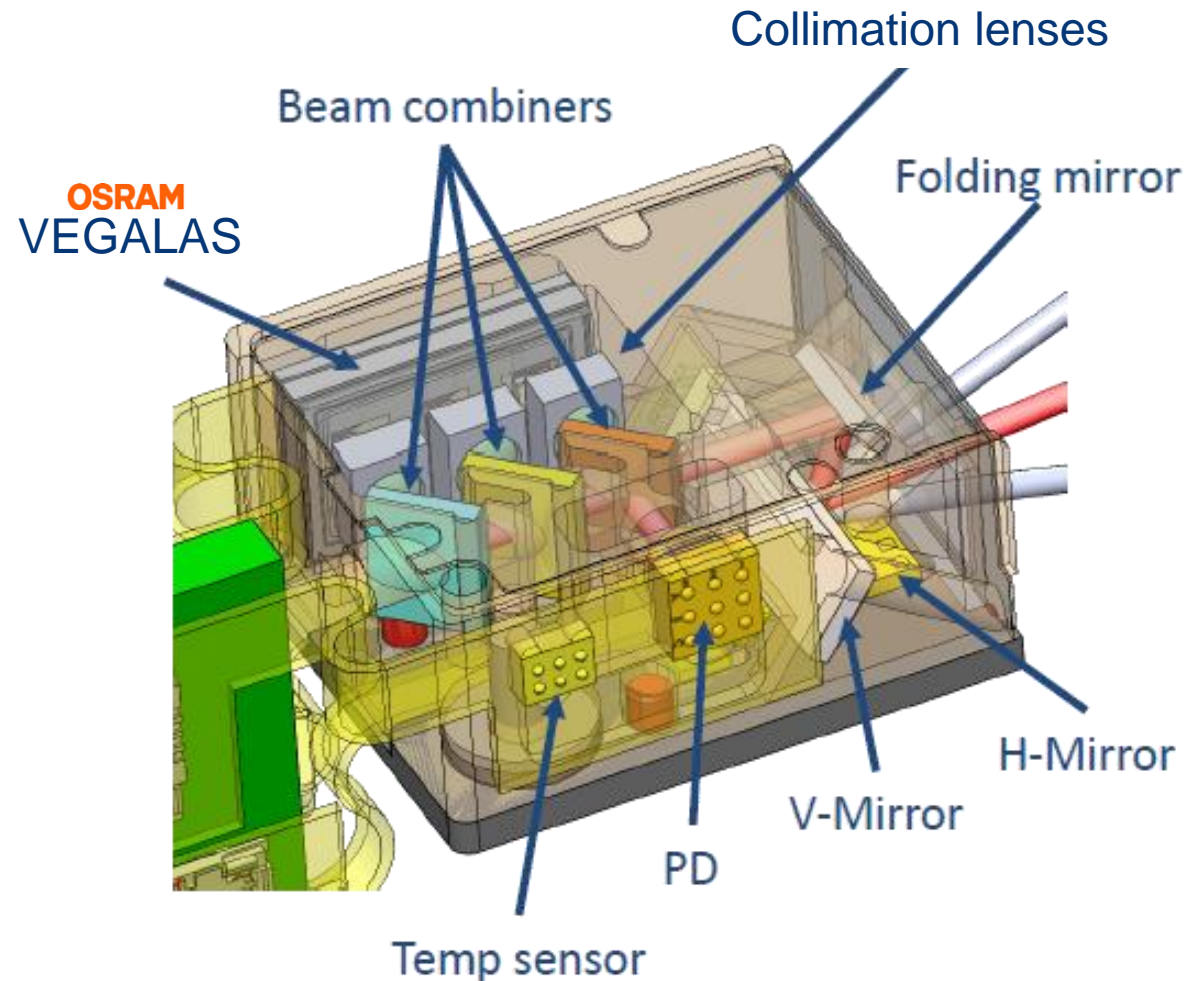
LBS Reference Design Architecture



- **MEMS Mirrors**
- **Mirrors Drivers**
 - Electrostatic, Magnetic, Piezo drivers
 - High efficiency / Energy recovery drivers
- **Laser Diodes Drivers**
 - <500ps rise/fall time for crisp pixels
 - Ultra low power – Optimized for AR
 - 3 / 4 channels (RGB / + IR)
- **Control Loops and Video**
 - HW / SW Mirror control loop
 - Laser control loop
 - Calibration
 - Video processing
- **Relay Optics**
 - ST patented design to maximize performances with waveguides



Anatomy of the ST LBS Optical Module



<https://www.spie.org/PWO/conferencedetails/moems-miniaturized-systems?SSO=1#session-1>

Session 6: Novel Optical Components II

Compact and innovative laser beam steering optical engine for smart glasses applications

Paper 11697-24

Author(s): Dadi Sharon, Elan Roth, Alex Domnits, Shlomi Erlich, STMicroelectronics Ltd. (Israel)

Putting it All Together – A Proof-of-Concept



Demo Specification		
FOV (diagonal)*	30°	24°(H)x18°(V)
Brightness	1300	cd/m ²
Image Aspect Ratio	4:3	
Eyebox	10 x 10	mm
Eye Relief	16	mm
Color	RGB	
Resolution	33	pixels/deg
Fresh Rate	60	Hz
Full System Weight	58	g

* Note: The FoV of the MEMS Mirror scanner is 56° diagonal

Images as Seen Through the Glasses



Trade-offs (system consideration)

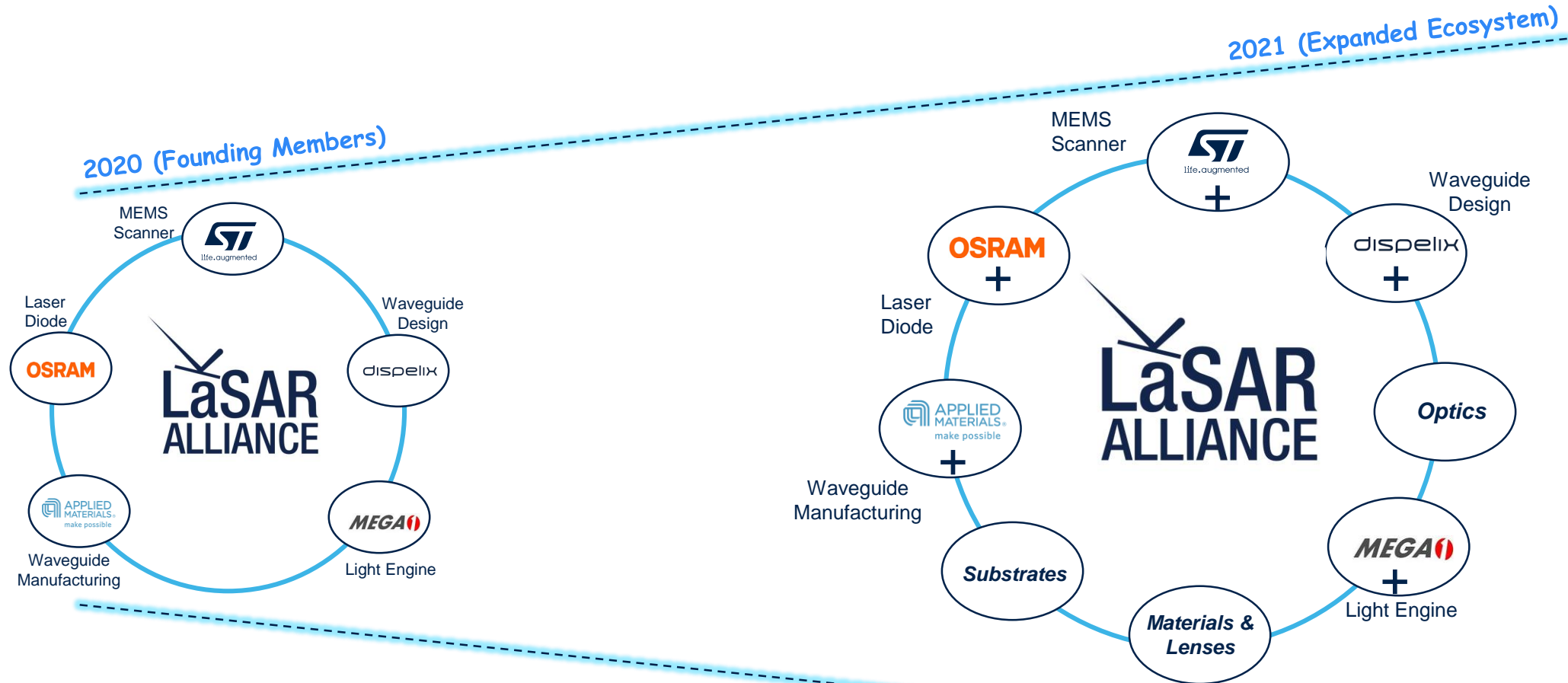
AR Glasses Design Tradeoff Considerations



Example only

- Design of AR wearables must be holistic in nature
- Optimize for the application
 - Simple text, symbology and graphical overlay
 - FoV ~ 30°-40°, >10mm eyebox, >1000 nits, <70g, monocular, eyeglass style
 - Fully immersive experience with holographic rendering
 - FoV >80°, >10mm eyebox, >500 nits, >1440P, <200g, binocular, HMD style
- LBS addresses a number of constraints and challenges

It Takes a Village: LaSAR Alliance Ecosystem



More Partners to be Announced
&
Open to More Members
Join the Alliance!

Thank you

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SPIE.ARVIMR

LaSAR
ALLIANCE

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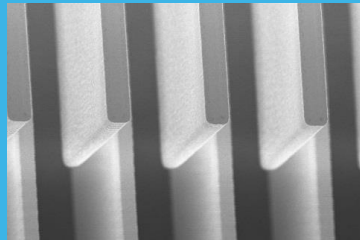


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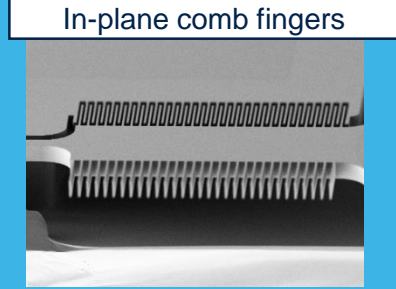
A wide range of mirror technologies in mass production

ST is the leader in LBS solutions with more than 12 million mirrors shipped to date

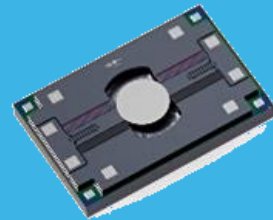
ELECTROSTATIC



Staggered comb fingers

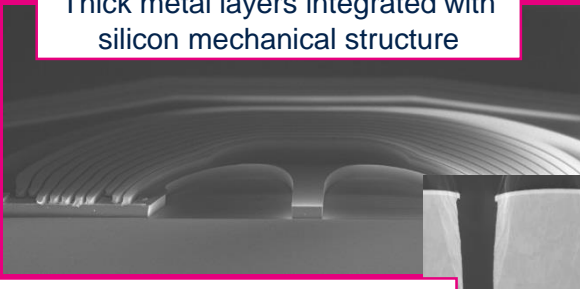


In-plane comb fingers



- High aspect ratio DRIE silicon etch for comb drive actuators (silicon thickness $\geq 40\mu\text{m}$), allowing both quasi-static and resonant operation
- Use of wafer-to-wafer bonding techniques to realize 3D integrated structures

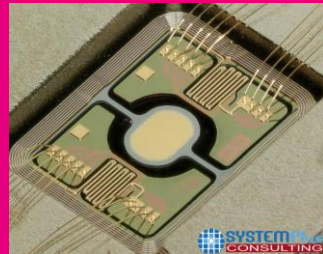
ELECTROMAGNETIC



Thick metal layers integrated with silicon mechanical structure



Thick metal cross section for coil

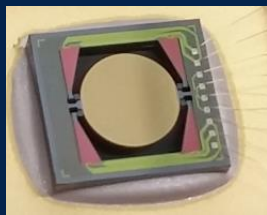


- Thick metal ECD growth ($>20\mu\text{m}$) to allow low resistance coil actuator
- Integrated piezoresistive position sensors
- Thin ($160\mu\text{m}$) finished holed wafers in production

PIEZO ELECTRIC

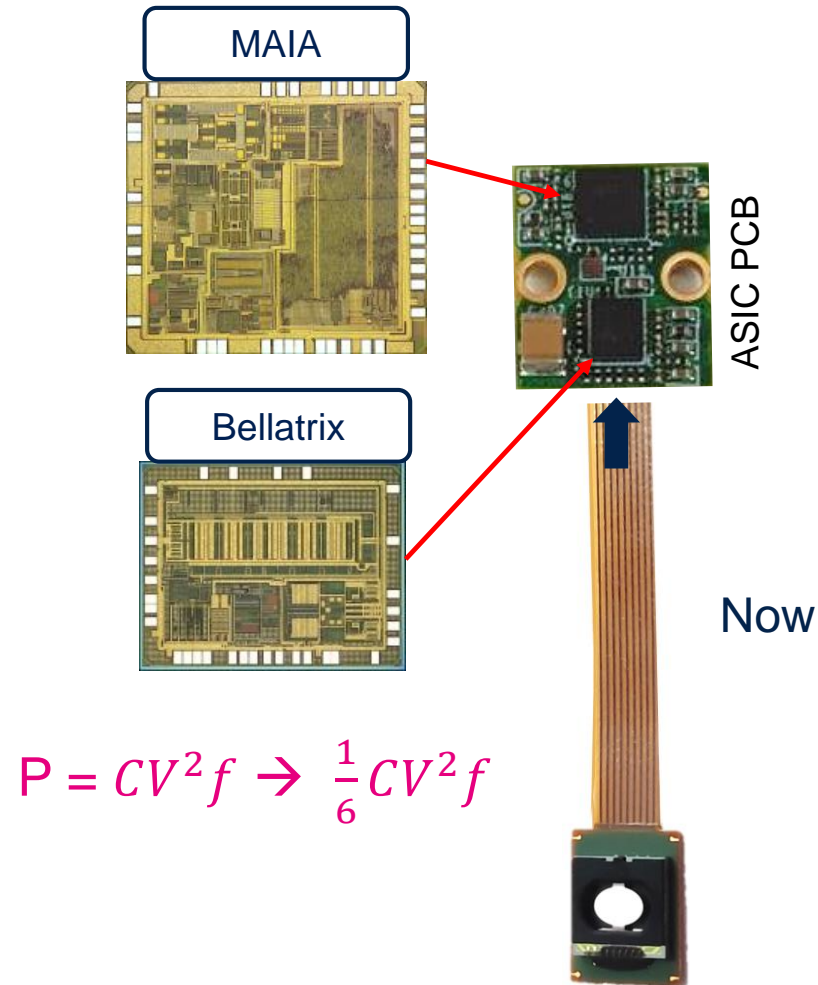


Thin Film PZT Mirror

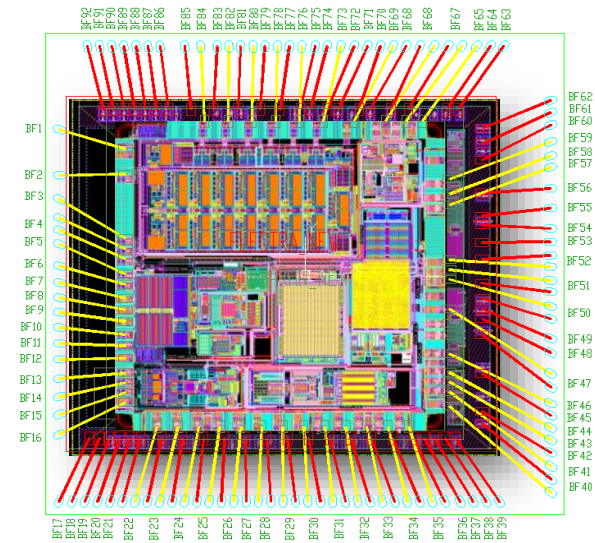
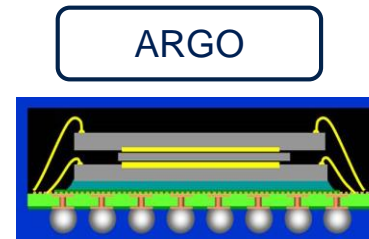
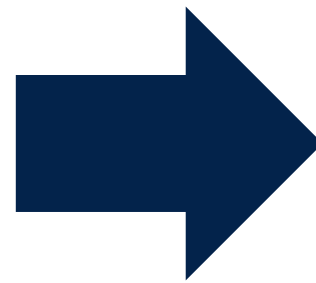


- Thin Film PZT ($\leq 2\mu\text{m}$), in Mass Production
- Integrated piezoresistive position sensor
- Use of wafer-to-wafer bonding for 3D integrated structures

High Efficiency TF PZT Drivers



$$P = CV^2f \rightarrow \frac{1}{6} CV^2f$$



Soon

$$\frac{1}{10} CV^2f$$

- Smaller footprint
- Less external components
- Fully Integrated Raster Scan (HW ctrl loop)

